



## Material Content Data Sheet



<b>Sales Product Name</b>		BSO080P03NS3E G		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA000650830						
<b>Package</b>		PG-DSO-8-39		<b>Weight*</b>		83.95 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.479	2.95	2.95	29531	29531
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		122	
	non noble metal	zinc	7440-66-6	0.041	0.05		488	
	non noble metal	iron	7439-89-6	0.820	0.98		9762	
wire	non noble metal	copper	7440-50-8	33.276	39.64	40.68	396378	406750
	non noble metal	copper	7440-50-8	0.335	0.40	0.40	3994	3994
	encapsulation	organic material	carbon black	1333-86-4	0.227	0.27		2702
plastics	plastics	epoxy resin	-	7.032	8.38		83763	
	inorganic material	silicondioxide	60676-86-0	38.108	45.39	54.04	453939	540404
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9694	9694
plating	noble metal	silver	7440-22-4	0.073	0.09	0.09	865	865
glue	plastics	epoxy resin	-	0.110	0.13		1314	
	noble metal	silver	7440-22-4	0.625	0.74	0.87	7448	8762
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com